SECURITIES AND EXCHANGE COMMISSION

WASHINGTON, D.C. 20549

FORM 8-K

CURRENT REPORT Pursuant to Section 13 or 15(d) of the Securities Exchange Act of 1934

Date of Report (Date of earliest event reported): March 20, 2018

DIODES INCORPORATED

(Exact name of Registrant as Specified in Its Charter)

Delaware (State or Other Jurisdiction of Incorporation) 002-25577 (Commission File Number) 95-2039518 (IRS Employer Identification No.)

4949 Hedgcoxe Road, Suite 200, Plano, TX (Address of Principal Executive Offices)

75024 (Zip Code)

Registrant's Telephone Number, Including Area Code: (972) 987-3900

Not Applicable (Former Name or Former Address, if Changed Since Last Report)

	the appropriate box below if the Form 8-K filing is intended to simultaneously satisfy the filing obligation of the registrant under any of the following provisions (see ral Instructions A.2. below):
	Written communications pursuant to Rule 425 under the Securities Act (17 CFR 230.425)
	Soliciting material pursuant to Rule 14a-12 under the Exchange Act (17 CFR 240.14a-12)
	Pre-commencement communications pursuant to Rule 14d-2(b) under the Exchange Act (17 CFR 240.14d-2(b))
	Pre-commencement communications pursuant to Rule 13e-4(c) under the Exchange Act (17 CFR 240.13e-4(c)) at by check mark whether the registrant is an emerging growth company as defined in Rule 405 of the Securities Act of 1933 (§230.405 of this chapter) or Rule 12b-2 of excurities Exchange Act of 1934 (§240.12b-2 of this chapter).
Emerg	ging growth company \Box
	emerging growth company, indicate by check mark if the registrant has elected not to use the extended transition period for complying with any new or revised financial nting standards provided pursuant to Section 13(a) of the Exchange Act.

Item 8.01 Other Events.

From time to time, Diodes Incorporated (the "Company") may give corporate presentations to its customers, suppliers and other related interested parties. Copies of the Company's corporate presentation slides, updated on March 20, 2018, are attached herewith as Exhibit 99.1.

Item 9.01 Financial Statements and Exhibits.

(d) Exhibits.

Exhibit <u>Number</u>

Description

99.1 Corporate Presentation Slides

Index to Exhibits

Exhibit Number

umber Description

99.1 <u>Corporate Presentation Slides</u>

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the Registrant has duly caused this report to be signed on its behalf by the undersigned hereunto duly authorized.

Dated: March 20, 2018 DIODES INCORPORATED

By /s/ Richard D. White

RICHARD D. WHITE Chief Financial Officer



Investor Meetings with Sidoti & Company

March 2018

Any statements set forth herein that are not historical facts are forward-looking statements that involve risks and uncertainties that could cause actual results to differ materially from those in the forward-looking statements. Such forward-looking statements include, but are not limited to, statements regarding updates to Diodes Incorporated's first quarter 2018 business outlook as of February 7, 2018, which include the following: expect revenue to range between \$261 million and \$277 million, or down 2.8 to up 3.2 percent sequentially; expect GAAP gross margin to be 36.0 percent, plus or minus 1 percent; non-GAAP operating expenses, which are GAAP operating expenses adjusted for amortization of acquisition-related intangible assets, are expected to be approximately 23.2 percent of revenue, plus or minus 1 percent; expect net interest expense to be approximately \$1.4 million; expect tax rate to be 31.0 percent, plus or minus 3 percent; shares used to calculate diluted EPS for the first quarter are anticipated to be approximately 51 million; purchase accounting adjustments for Pericom and previous acquisitions of \$3.8 million after tax are not included in these non-GAAP estimates; and other statements identified by words such as "estimates," "expects," "projects," "plans," "will," and similar expressions.

Potential risks and uncertainties include, but are not limited to, such factors as: the risk that such expectations may not be met: the risk that the expected benefits of acquisitions may not be realized or that integration of acquired businesses, such as Pericom, may not continue as rapidly as we anticipate; the risk that we may not be able to maintain our current growth strategy or continue to maintain our current performance, costs, and loadings in our manufacturing facilities; the risk that we may not be able to increase our automotive or other revenue and market share; risks of domestic and foreign operations, including excessive operation costs, labor shortages, higher tax rates, and our joint venture prospects; the risk that we may not continue our share repurchase program; the risks of cyclical downturns in the semiconductor industry and of change sin end-market demand or product mix that may affect gross margin or render inventory obsolete; the risk of unfavorable currency exchange rates; the risk that our future outlook or guidance may be incorrect; the risks of global economic weakness or instability in global financial markets; the risks of trade restrictions, tariffs, or embargoes; the risk of breaches of our information technology systems; and other information, including the "Risk Factors" detailed from time to time in Diodes' filings with the United States Securities and Exchange Commission.

This presentation also contains non-GAAP measures. See the Company's press release on February 7, 2018 titled, "Diodes Incorporated Reports Fourth Quarter and Fiscal 2017 Financial Results" for detailed information related to the Company's non-GAAP measures and a reconciliation of GAAP net income to non-GAAP net income.





Rick White CFO and Secretary

CFO Since 2009 SR VP, Finance 3 years Texas Instruments 25 years

Experience:

- Partner, Tatum Partners
- CFO, Optisoft
- Vice President, TI Worldwide, Memory

Education:

- · MBA, Finance, University of Michigan
- Bachelor's Degree, Electrical Engineering, Oklahoma State University



Laura Mehrl (冯蓉媞)

Company spokesperson, Director of Investor Relations Since May 2010

Experience:

- Director of Investor Relations, Diodes Incorporated, Plano, Texas
- Senior Business Development Manager, STMicroelectronics, Carrollton, Texas
- Sales Director for Analog Devices Inc., Shanghai, China
- Product Marketing Manager at Texas Instruments (TI), Dallas, Texas
- Senior Engineer at Lattice Semiconductor Inc., Hillsboro, Oregon
- Wafer fab design engineer and product engineer at TI, Lubbock, Texas

Education:

- MBA with concentration in International Marketing, Texas Tech University
- BS in Electrical and Computer Engineering, University of Iowa



A leading global manufacturer and supplier of high-quality application specific, standard products within the broad discrete, logic and analog markets, serving the consumer, computing, communications, Industrial and automotive segments.





Global Operations and World-class Manufacturing & Packaging

- NASDAQ: DIOD
- Founded in 1959
- Headquartered in Plano, TX; 21 locations globally
- Manufacturing in UK, Germany, China and Taiwan
- ISO9001:2008 Certified / TS16949:2009 Certified ISO14001 Certified
- Key acquisitions:
 - Anachip Corporation, Taiwan Jan. 2006
 - Advanced Power Devices Nov. 2006
 - Zetex June 2008

 - BCD Semiconductor Mar. 2013
 - Pericom Semiconductor Nov. 2015
- Over 7,692 employees worldwide
- 26 consecutive years of profitability

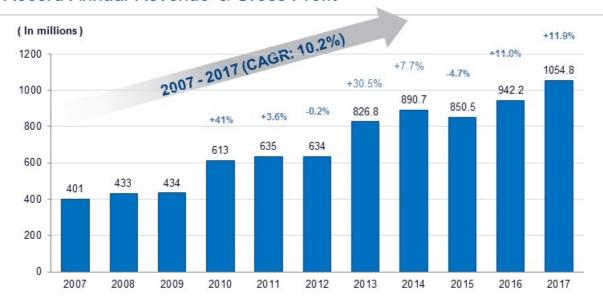








2017: Record Annual Revenue & Gross Profit



Achieved milestone of \$1 Billion in Annual Revenue in Fiscal 2017





Mission:

Profitability growth to expand shareholder value

Strategy:

Grow revenue to \$2.5B at 40% GPM

Goal:

\$1B Gross Profit by 2025





	2017		2025
NR	\$1B	\rightarrow	2.5B
GP%	35%	\rightarrow	40%
GPM	\$3501	\$350M →	
R&D%	5%	\rightarrow	7%
SG&A%	15%	\rightarrow	13%
PFO	15%	\rightarrow	20%





Automotive

Adaptive lighting, body controls and connected driving

Industrial

Embedded systems and precision controls

Consumer

IoT: Wearables, home automation, and smart infrastructure

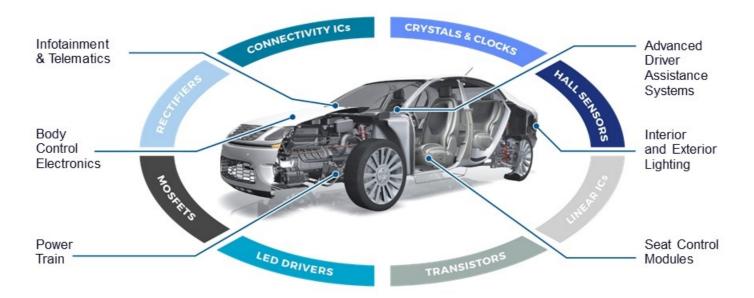
Communication

- Smart phones: advanced protocols and charging

Computing

Cloud computing: server, storage and data centers







Connected driving

- ADAS (Advanced Driver Assistance Systems)
- Telematics
- Infotainment Systems

Comfort, style and safety

- Lighting
 - Migration to LED and intelligent illumination
- Brushless Motor Control (BLDC)
 - Migrating from Brushed to Brushless DC Motors

Electrification/Powertrain

- Conventional Powertrain → Hybrid → Electrification
- Battery management
 - Move to 48V battery



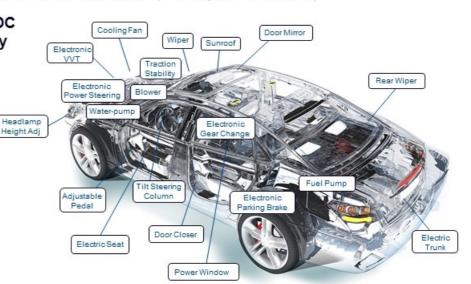


Migrating from Brushed to BLDC Motors (~ 30 per vehicle)

Automotive market moving to BLDC motors for reliability and efficiency

 Forecast to grow to 3.8 Billion units by 2021

Diodes Key Products	\$/Car
MOSFETs	\$18.75
Diodes Rectifiers	\$2.60
Hall Sensors	\$0.50
Gate Drivers	\$1.50
Crystals/XO	\$2.00
Total	\$25.35



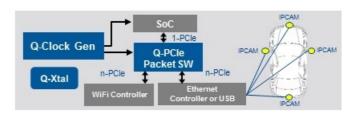


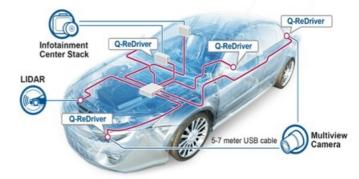
Higher speed data rates and increased number of channels

Robust and reliable data transfer

- ADAS, Telematics and Infotainment systems are merging into Connected Driving
- Forecast to grow to 280 Million units by 2021

Diodes Key Products	\$ Per Car
Connectivity: (PCle SW + ReDrivers, Signal SW, USB charger)	\$8.50
Crystal/XO & Clocks	\$3.50
Automotive Analog IC	\$1.52
MOSFETs, BJT	\$6.62
Diodes & Rectifiers	\$3.60
Total	\$ 23.74







Diodes can address \$70 of semiconductor content per vehicle.

Diodes Key Products	\$/Car
Analog	\$2.02
Power Management	\$5.99
MOS/BJT	\$35.02
Diodes & Rectifiers	\$12.69
Timing & Connectivity	\$15.03
Total	\$70.75

With 95M vehicles built in 2017, Diodes addressable SAM is \$6.7 Billion.

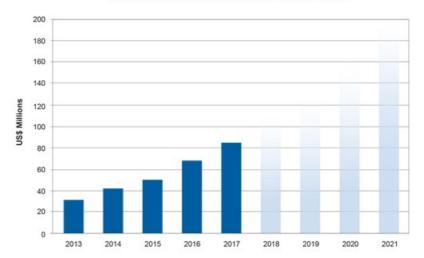




* SemiCast Automotive Report 2016 forecast

- Automotive revenue 27%
 CAGR 2013 to 2017
- Automotive now represents 8% of Diodes' total revenue
- Automotive will continue to be an increasingly significant market segment for Diodes

Diodes' Automotive Revenue





- Increasing IC content in embedded systems
- Switching and signal path for networked systems and automation
- Signal conditioning and timing for precision controls
- Motor controls, sensors and power management for smart meters





Smart Infrastructure



Consumer & Home



Asset Tracking











 Ultra low power for battery operated, loT applications







Enterprise Security & Surveillance

 Noise immunity for integrated cameras and sensors



- Focus on signal integrity and higher data rates
- Proliferation of USB Type-CTM connectivity and power delivery
- Power regulation and protection for new features
- Advanced power solutions for quick charge protocols





- USB-C controller with USB3.1 Gen1/Gen2 offer the best solution in the market for high level of integration, best signal integrity, lowest power dissipation
- Linear redrivers handle longer channels, transparency to end nodes' link training, and power saving features
- Power switches offer comprehensive integrated protection features, high voltage operation, smooth transition to fast role swap and small packages
- Transient Voltage Suppressor offerings provide very low capacitance, protection against high surge voltage, and small packages
- DC-DC converters offer high efficiency, high current handling, and low EMI
- AC-DC Adapter/Charger solution offer high efficiency, low standby current, quick charging



Type-C controller with Mux: PI5USB31213A

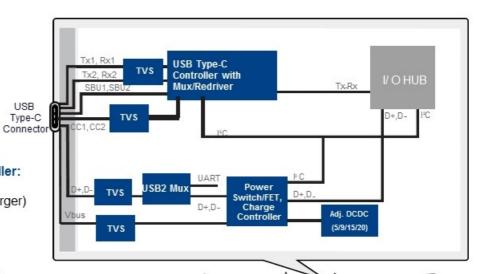
ReDriver/Active Mux:
 PI3EQX1002B(USB3.1 Gen2),
 PI3EQX1012C (USB3.1 Gen2
 Active mux)

USB2/Audio Switch: PI3USB102J, PI3DBS3224, PI3USB223

Power Switch, FET, Charge Controller: DPS1133 (Source) DPS1035 (Sink), DMT3006 (FET), PI5USB2546A (Charger)

DCDC: AP6503

 TVS: DT3V3F4U10LP (SS), D5VDH1U2LP (CC), DESD3V3S1BL (SBU), D15VDH1U2LP16 (VBUS)

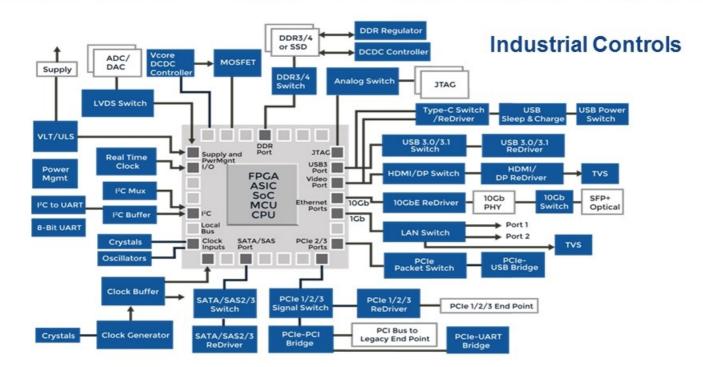




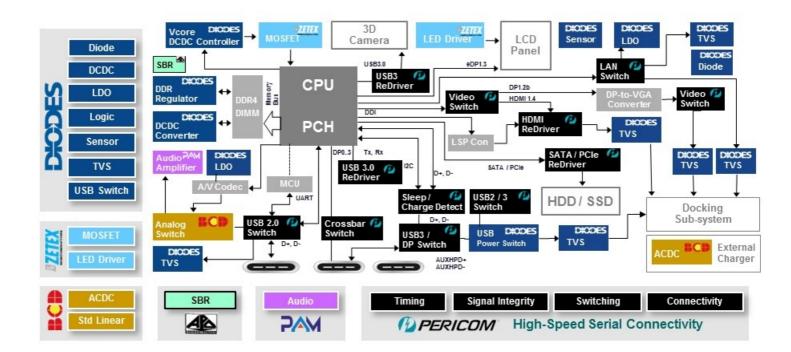


- ReDriver support for USB connectivity
- Wide range of signal protocols: PCIe, SAS, SATA, GbE, USB
- MUX products for high capacity solid state storage
- Crystal oscillators for increasing clocking speeds









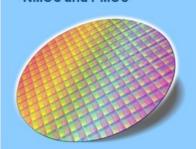


Products Dropes 20Ghps ReDrivers and

- 20Gbps ReDrivers and Switches
- Automotive Packet Switch for Telematics / ADAS
- Complete USB Type-C™ Signal Switching
- High speed clocking for cloud computing
- Ultra low power and low noise LDOs for IoT
- Low Cj TVS for signal integrity
- Lowest rps(on) LDMOS for battery efficiency

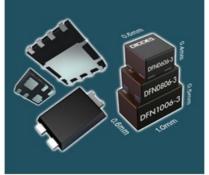
Wafer Fab

- High performance 8" MOSFET trench technology
- Advanced Epi bipolar transistor processes
- Proprietary rectifier technology
- Rugged automotive grade NMOS and PMOS



Assembly/Test

- Compact QFN and DFN
- Power density PowerDI
- Chip scale packaging and plating capability
- Extensive multi-chip package technology





Focus: Miniaturization and Power Efficiency



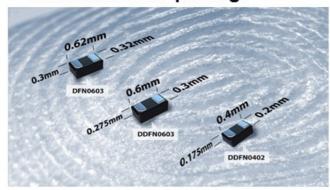
DIODES.

Current 2018+

Miniaturization and Multi-Chip Packaging

Miniaturization DDFN0402

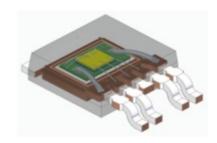
the smallest discrete semiconductor package



Multi-Chip Packaging

Dual-Flat No-Lead (DFN) DDFN (Encapsulated CSP)Chip-Scale Package (CSP)

HS IntelliFET: ZXMS3001







Packaging

- Shanghai-based packaging with capacity over 34 billion units
- Chengdu facility has potential capacity 3X of Shanghai
- Additional facilities in Neuhaus, Germany and Chengdu, China



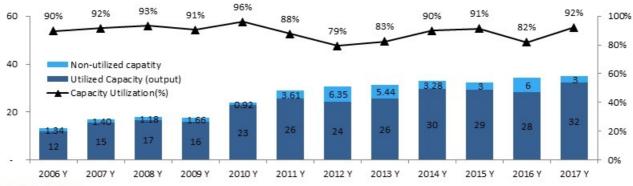
Wafer Fabs

- Two fabs in Shanghai (6" and 8"), one discrete fab in Oldham, UK (6")
- Bipolar, BiCMOS, CMOS and BCD process
- Strong engineering capabilities



Economies of Scale: Capacity & Loading Percentage in SAT

*CapEx Model = 5% - 9% of Revenue





FINANCIAL OVERVIEW

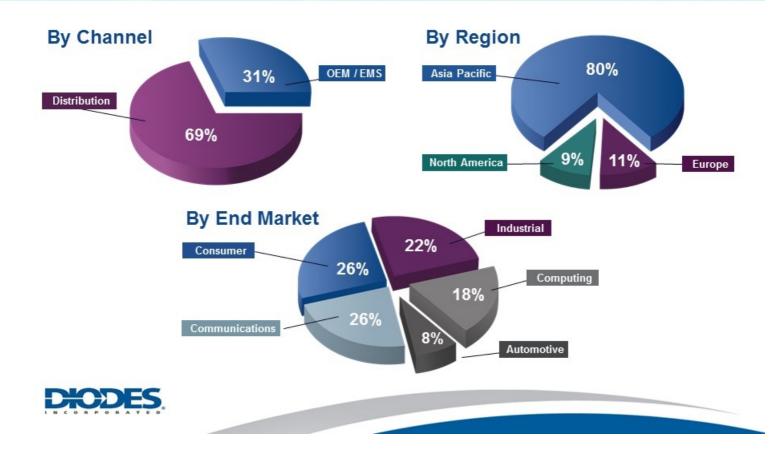


In millions, except per share	4Q16	3Q17	4Q17	YoY
Revenue	\$232.1	\$285.2	\$268.4	15.7%
Gross Profit (GAAP)	\$67.3	\$96.3	\$96.4	43.2%
Gross Profit Margin % (GAAP)	29.0%	33.8%	35.9%	+690bp
Net Income (GAAP)	\$1.3	\$14.5	(\$30.7)	
Net Income (non-GAAP)	\$7.7	\$22.6	\$21.6	
EPS (non-GAAP)	\$0.15	\$0.45	\$0.42	280%
Cash Flow from Operations	\$33.1	\$40.9	\$74.8	
EBITDA (non-GAAP)	\$29.2	\$46.8	\$46.9	60.6%
EBITDA (non-GAAP)	2015 129.5	2016 133.3	2017 168.2	26.2%



- Revenue grew 11.9% to a record \$1.05 billion due to continued market share gains in all regions;
- GAAP gross profit was a record \$356.8 million, and non-GAAP gross profit for 2017 was \$359.5 million;
- GAAP gross margin improved 330 basis points to 33.8%, and non-GAAP gross margin was 34.1%;
- GAAP net loss was (\$1.8) million, or (\$0.04) per diluted share;
- Non-GAAP adjusted net income increased 80.1%to \$69.1 million, or \$1.37 per diluted share;
- Excluding \$12.1 million, net of tax, non-cash share-based compensation expense, both GAAP net income and non-GAAP adjusted net income would have increased by \$0.24 per diluted share; and
- Achieved \$181.1 million cash flow from operations and \$70.0 million free cash flow, including \$111.2 million of capital expenditures, or 10.5% of revenue. Net cash flow was negative (\$44.0) million, which includes the pay down of \$159.9 million of long-term debt and \$8.7 million for the stock buyback.





In millions	Dec 31, 2015	Dec 31, 2016	Dec 31, 2017
Cash	\$218	\$248	\$204
Short-term Investments	\$65	\$30	\$5
Inventory	\$203	\$193	\$217
Current Assets	\$751	\$733	\$662
Total Assets	\$1599	\$1531	\$1489
Long-term Debt	\$454	\$413	\$247
Total Liabilities	\$756	\$708	\$615
Total Equity	\$843	\$820	\$874



- Revenue to range between \$261 million and \$277 million, or down 2.8% to up 3.2%. At the mid point, this is flat to fourth quarter and represents a 13.8 percent increase year-over-year
- GAAP gross margin to be 36.0%, plus or minus 1%
- Non-GAAP operating expenses, which are GAAP operating expenses adjusted for amortization of acquisition-related intangible assets, are expected to be approximately 23.2% of revenue, +/- 1%
- Interest expense to be approximately \$1.4 million, and income tax rate is expected to be 31.0%, +/- 3%
- Shares used to calculate diluted EPS approximately 51 million
- Purchase accounting adjustments for Pericom and previous acquisitions of \$3.8 million after tax are not included in non-GAAP estimates

*Guidance as provided on February 7, 2018



Summary Page 37

- Vision: Expand shareholder value
- Mission: Profitability growth to drive 20% PFO
- Next Strategic Goal: \$1B gross profit
- Strategy: \$2.5B revenue at 40% GPM
- Tactics:
 - Increased focus on Automotive and Industrial markets
 - Investment for technology leadership in target products, fab processes, and advanced packaging
 - Systems solutions to drive business expansion



